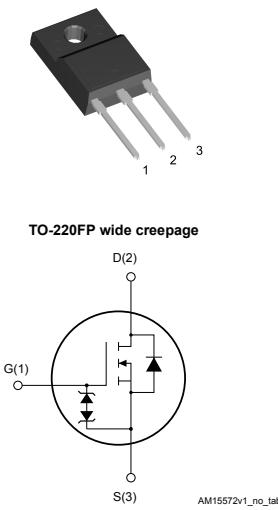


## N-channel 600 V, 0.55 Ω typ., 7.5 A MDmesh M2 Power MOSFET in a TO-220FP wide creepage package



### Features

Order code	V <sub>DS</sub> at T <sub>Jmax.</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STFH10N60M2	650 V	0.60 Ω	7.5 A

- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected
- Wide distance of 4.25 mm between the pins

### Applications

- Switching applications
- LLC converters, resonant converters

### Description

This device is an N-channel Power MOSFET developed using MDmesh M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

The TO-220FP wide creepage package provides increased surface insulation for Power MOSFETs to prevent failure due to arcing, which can occur in polluted environments.



Product status link	
<a href="#">STFH10N60M2</a>	
Product summary	
Order code	STFH10N60M2
Marking	10N60M2
Package	TO-220FP wide creepage
Packing	Tube

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$ <sup>(1)</sup>	Drain current (continuous) at $T_C = 25^\circ\text{C}$	7.5	A
	Drain current (continuous) at $T_C = 100^\circ\text{C}$	4.9	
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	30	A
$P_{TOT}$	Total power dissipation at $T_C = 25^\circ\text{C}$	25	W
$dv/dt$ <sup>(3)</sup>	Peak diode recovery voltage slope	15	V/ns
$dv/dt$ <sup>(4)</sup>	MOSFET dv/dt ruggedness	50	
$V_{ISO}$ <sup>(5)</sup>	Insulation withstand voltage (RMS) from all three leads to external heat sink	2500	V
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

1. Limited by package.
2. Pulse limited by safe operating area.
3.  $I_{SD} \leq 7.5 \text{ A}$ ,  $di/dt \leq 400 \text{ A}/\mu\text{s}$ ;  $V_{DS}$  peak <  $V_{(BR)DSS}$ ,  $V_{DD} = 400 \text{ V}$
4.  $V_{DS} \leq 480 \text{ V}$ .
5.  $t = 1 \text{ s}$ ;  $T_C = 25^\circ\text{C}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	5	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance, junction-to-ambient	62.5	

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$ <sup>(1)</sup>	Avalanche current, repetitive or not repetitive	1.5	A
$E_{AS}$ <sup>(2)</sup>	Single pulse avalanche energy	110	mJ

1. Pulse width limited by  $T_{jmax}$ .
2. Starting  $T_j = 25^\circ\text{C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50 \text{ V}$ .

## 2 Electrical characteristics

( $T_{case} = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_{case} = 125^\circ\text{C}$ <sup>(1)</sup>			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		0.55	0.60	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	400	-	pF
$C_{oss}$	Output capacitance		-	22	-	
$C_{rss}$	Reverse transfer capacitance		-	0.84	-	
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	83	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	6.4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 7.5 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 15. Test circuit for gate charge behavior)	-	13.5	-	nC
$Q_{gs}$	Gate-source charge		-	2.1	-	
$Q_{gd}$	Gate-drain charge		-	7.2	-	

1.  $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

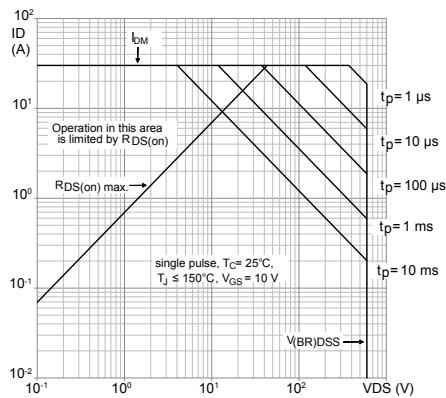
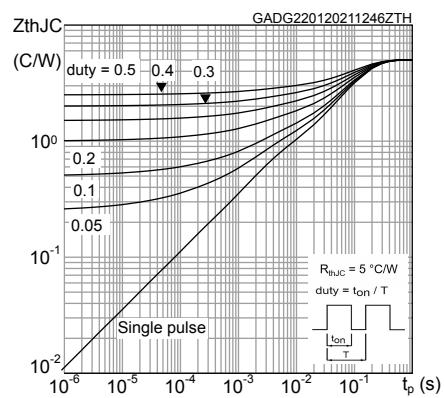
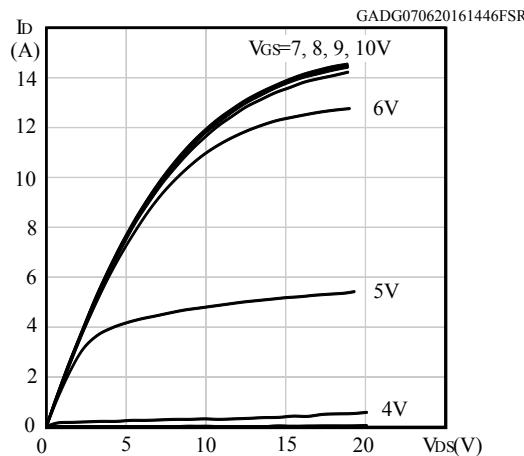
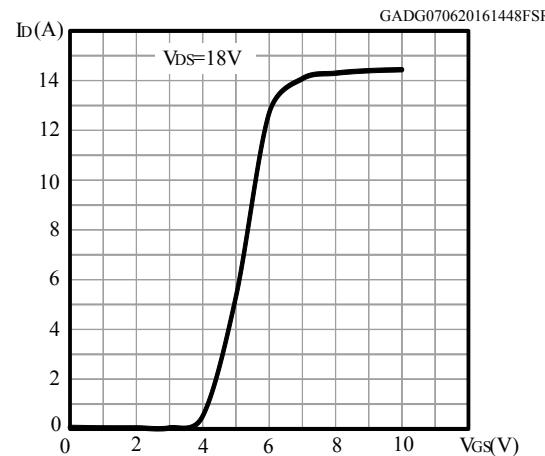
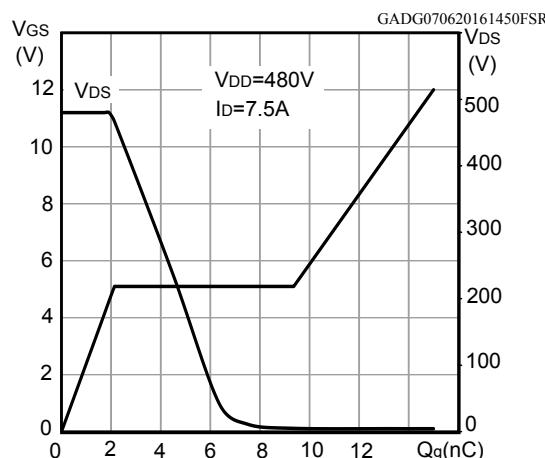
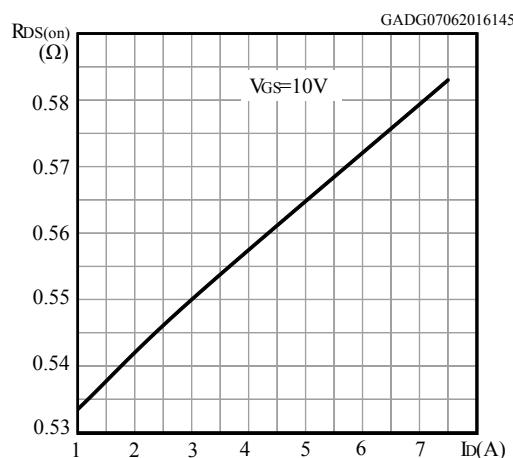
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 3.75 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	8.8	-	ns
$t_r$	Rise time		-	8	-	
$t_{d(off)}$	Turn-off delay time		-	32.5	-	
$t_f$	Fall time		-	13.2	-	

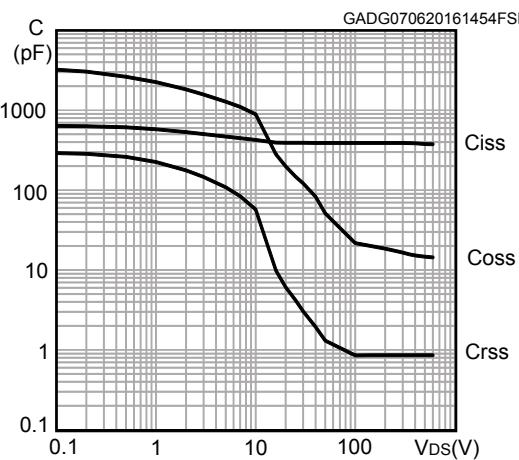
Table 7. Source-drain diode

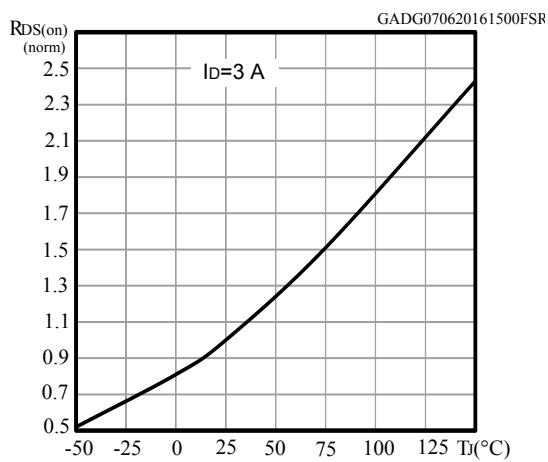
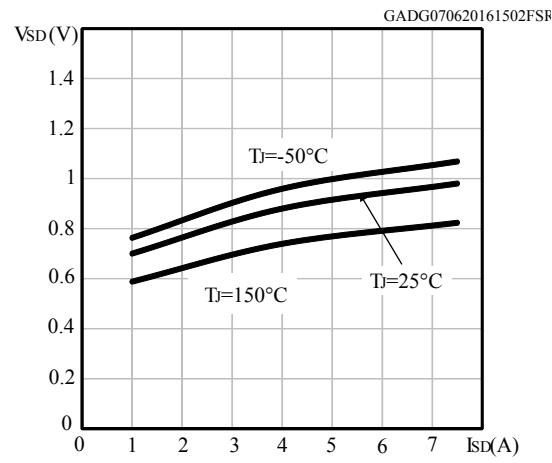
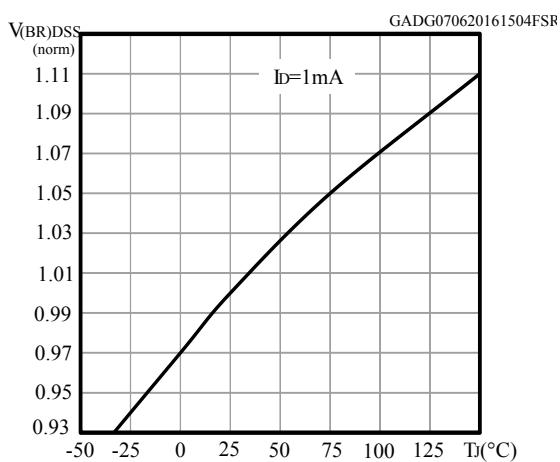
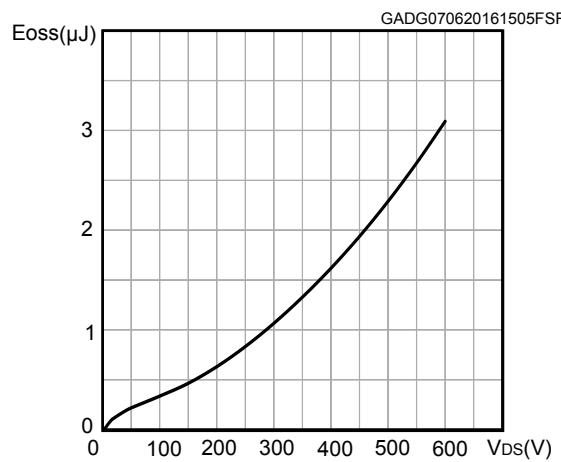
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ <sup>(1)</sup>	Source-drain current		-		7.5	A
$I_{SDM}$ <sup>(2)</sup>	Source-drain current (pulsed)		-		30	A
$V_{SD}$ <sup>(3)</sup>	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 7.5 \text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 7.5 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ (see ) Figure 16. Test circuit for inductive load switching and diode recovery times	-	270		ns
$Q_{rr}$	Reverse recovery charge		-	2		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	14.4		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 7.5 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ , $T_j = 150 \text{ }^\circ\text{C}$ (see ) Figure 16. Test circuit for inductive load switching and diode recovery times	-	376		ns
$Q_{rr}$	Reverse recovery charge		-	2.8		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	15		A

1. Limited by package.
2. Pulse width is limited by safe operating area.
3. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics curves

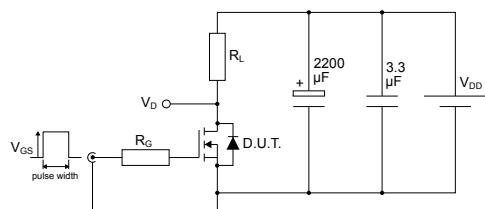
**Figure 1. Safe operating area**

**Figure 2. Maximum transient thermal impedance**

**Figure 3. Output characteristics**

**Figure 4. Transfer characteristics**

**Figure 5. Gate charge vs gate-source voltage**

**Figure 6. Static drain-source on-resistance**


**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Source-drain diode forward characteristics**

**Figure 11. Normalized  $V_{(BR)DSS}$  vs temperature**

**Figure 12. Output capacitance stored energy**


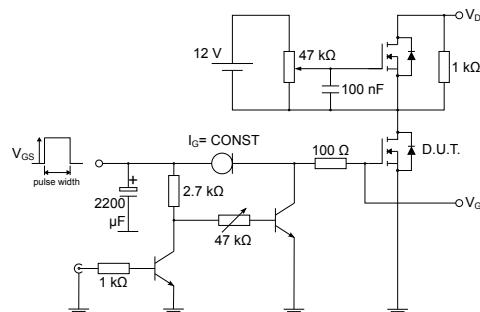
### 3 Test circuits

**Figure 13.** Test circuit for resistive load switching times



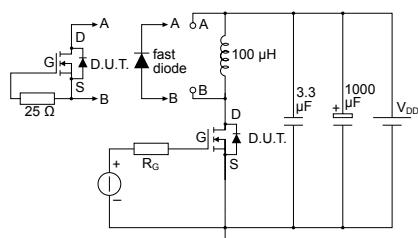
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**Figure 14.** Test circuit for gate charge behavior



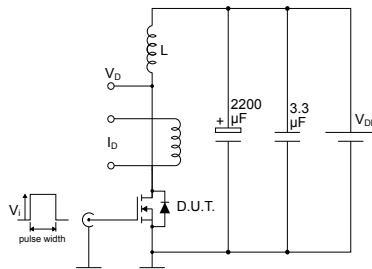
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**Figure 15.** Test circuit for inductive load switching and diode recovery times



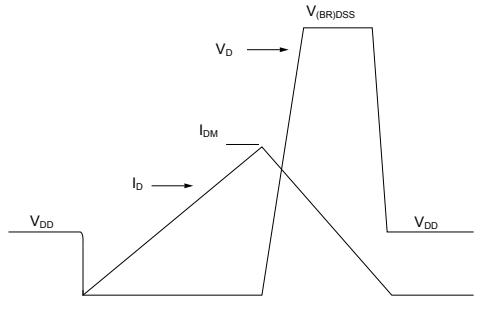
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**Figure 16.** Unclamped inductive load test circuit



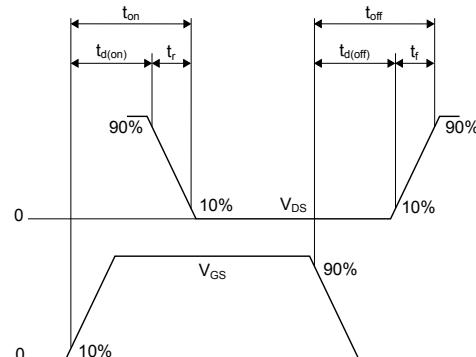
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**Figure 17.** Unclamped inductive waveform



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**Figure 18.** Switching time waveform



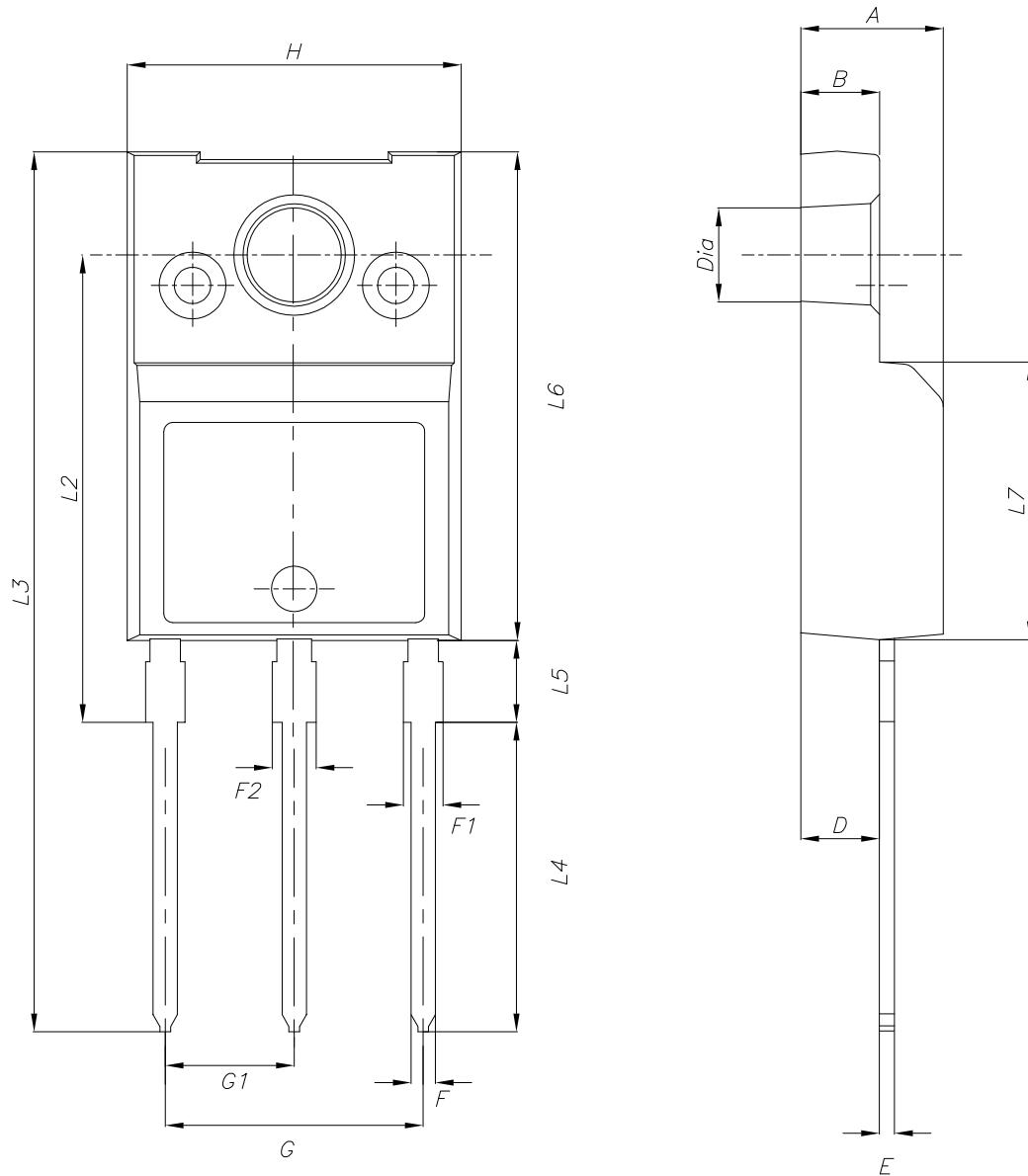
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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-220FP wide creepage package information

Figure 19. TO-220FP wide creepage package outline



DM00260252\_1

Table 8. TO-220FP wide creepage package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.70	4.80
B	2.50	2.60	2.70
D	2.49	2.59	2.69
E	0.46		0.59
F	0.76		0.89
F1	0.96		1.25
F2	1.11		1.40
G	8.40	8.50	8.60
G1	4.15	4.25	4.35
H	10.90	11.00	11.10
L2	15.25	15.40	15.55
L3	28.70	29.00	29.30
L4	10.00	10.20	10.40
L5	2.55	2.70	2.85
L6	16.00	16.10	16.20
L7	9.05	9.15	9.25
Dia	3.00	3.10	3.20

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
07-Jun-2016	1	First release.
16-Jun-2016	2	Document status promoted from preliminary data to production data. Minor text changes.
18-Aug-2016	3	Modified: title and $R_{DS(on)}$ in cover page Modified: <i>Table 5: "On /off states"</i> and <i>Table 7: "Switching times"</i> Minor text changes
08-May-2017	4	Modified features on cover page. Modified Table 1 and Table 3. Minor text changes.
29-Jan-2021	5	Updated <a href="#">Figure 1</a> and <a href="#">Figure 2</a> . Minor text changes.

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